



flowPACK 1

650 V / 50 A

Topology features

- Inverter
- Kelvin Emitter for improved switching performance
- Temperature sensor

Component features

- High speed and smooth switching
- Low gate charge
- Very low collector emitter saturation voltage

Housing features

- Base isolation: Al₂O₃
- Convex shaped substrate for superior thermal contact
- Thermo-mechanical push-and-pull force relief
- Solder pin

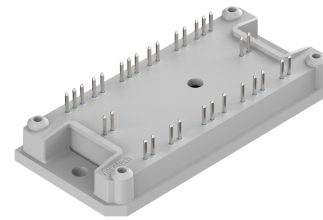
Target applications

- Energy Storage Systems
- Solar Inverters

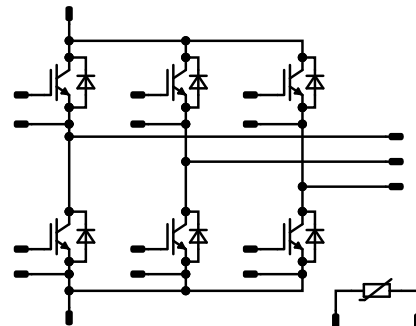
Types

- 10-FY076PA050S501-L822F58

flow 1 12 mm housing



Schematic





Vincotech

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|-----------------------------------|------------|---------------------------------------|----------|------|
| Inverter Switch | | | | |
| Collector-emitter voltage | V_{CES} | | 650 | V |
| Collector current (DC current) | I_C | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 48 | A |
| Repetitive peak collector current | I_{CRM} | t_p limited by T_{jmax} | 150 | A |
| Total power dissipation | P_{tot} | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 73 | W |
| Gate-emitter voltage | V_{GES} | | ± 20 | V |
| Maximum junction temperature | T_{jmax} | | 175 | °C |

Inverter Diode

| | | | | |
|---------------------------------|------------|---------------------------------------|-----|----|
| Peak repetitive reverse voltage | V_{RRM} | | 650 | V |
| Forward current (DC current) | I_F | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 46 | A |
| Repetitive peak forward current | I_{FRM} | t_p limited by T_{jmax} | 100 | A |
| Total power dissipation | P_{tot} | $T_j = T_{jmax}$ $T_s = 80\text{ °C}$ | 68 | W |
| Maximum junction temperature | T_{jmax} | | 175 | °C |

Module Properties

Thermal Properties

| | | | | |
|---|-----------|--|----------------------------|----|
| Storage temperature | T_{stg} | | -40...+125 | °C |
| Operation temperature under switching condition | T_{jop} | | -40...+($T_{jmax} - 25$) | °C |

Isolation Properties

| | | | | |
|----------------------------|------------|-------------------------------------|------------|----|
| Isolation voltage | V_{isol} | DC Test Voltage* $t_p = 2\text{ s}$ | 6000 | V |
| Isolation voltage | V_{isol} | AC Voltage $t_p = 1\text{ min}$ | 2500 | V |
| Creepage distance | | | >12,7 | mm |
| Clearance | | | 7,81 | mm |
| Comparative Tracking Index | CTI | | ≥ 600 | |

*100 % tested in production



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Characteristic Values

| Parameter | Symbol | Conditions | | | | | Values | | | Unit |
|-----------|--------|--------------|--------------|--------------|-----------|-------------------------------------|------------|-----|-----|------|
| | | V_{GS} [V] | V_{GE} [V] | V_{DS} [V] | V_F [V] | I_C [A] I_D [A] I_F [A] | T_j [°C] | Min | Typ | |

Inverter Switch

Static

| | | | | | | | | | | |
|--------------------------------------|---------------|-------------------|----|-----|--------|------------------|-----|----------------------|---------------------|----|
| Gate-emitter threshold voltage | $V_{GE(th)}$ | $V_{CE} = V_{GE}$ | | | 0,0005 | 25 | 3,2 | 4 | 4,8 | V |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | | 15 | | 50 | 25 125 150 | | 1,39 1,48 1,51 | 1,75 ⁽¹⁾ | V |
| Collector-emitter cut-off current | I_{CES} | | 0 | 650 | | 25 | | | 50 | μA |
| Gate-emitter leakage current | I_{GES} | | 20 | 0 | | 25 | | | 100 | nA |
| Internal gate resistance | r_g | | | | | | | None | | Ω |
| Input capacitance | C_{ies} | | | | | | | 3100 | | pF |
| Output capacitance | C_{oes} | $f = 1$ Mhz | 0 | 25 | | 25 | | 88 | | pF |
| Reverse transfer capacitance | C_{res} | | | | | | | 12 | | pF |
| Gate charge | Q_g | $V_{CC} = 520$ V | 15 | | 50 | 25 | | 120 | | nC |

Thermal

| | | | | | | | | | | |
|--|---------------|---------------------------------------|--|--|--|--|--|------|--|-----|
| Thermal resistance junction to sink ⁽²⁾ | $R_{th(j-s)}$ | $\lambda_{paste} = 3,4$ W/mK (PSX) | | | | | | 1,29 | | K/W |
|--|---------------|---------------------------------------|--|--|--|--|--|------|--|-----|

Dynamic

| | | | | | | | | | | |
|-----------------------------|--------------|---|--|--|--|------------------|--|-------------------------|--|-----|
| Turn-on delay time | $t_{d(on)}$ | | | | | 25 125 150 | | 23,72 24,17 24,12 | | ns |
| Rise time | t_r | | | | | 25 125 150 | | 7,36 8,64 9,14 | | ns |
| Turn-off delay time | $t_{d(off)}$ | | | | | 25 125 150 | | 72,46 88,73 92,68 | | ns |
| Fall time | t_f | | | | | 25 125 150 | | 17,74 38,16 42,72 | | ns |
| Turn-on energy (per pulse) | E_{on} | $Q_{tFWD} = 1,51$ μC $Q_{tFWD} = 3,1$ μC $Q_{tFWD} = 3,57$ μC | | | | 25 125 150 | | 0,266 0,406 0,453 | | mWs |
| Turn-off energy (per pulse) | E_{off} | | | | | 25 125 150 | | 0,554 0,849 0,953 | | mWs |



Characteristic Values

| Parameter | Symbol | Conditions | | | | | Values | | | Unit |
|--|----------------------|---|---|-------------------------------------|------------|-----------|--------|--------------|---------------------|------|
| | | V_{GE} [V] V_{GS} [V] | V_{CE} [V] V_{DS} [V] V_F [V] | I_C [A] I_D [A] I_F [A] | T_j [°C] | Min | Typ | Max | | |
| Inverter Diode | | | | | | | | | | |
| Static | | | | | | | | | | |
| Forward voltage | V_F | | | | 50 | 25 125 | 1,18 | 1,63 1,53 | 1,82 ⁽¹⁾ | V |
| Reverse leakage current | I_R | $V_r = 650$ V | | | | 25 | | | 0,6 | μA |
| Thermal | | | | | | | | | | |
| Thermal resistance junction to sink ⁽²⁾ | $R_{th(j-s)}$ | $\lambda_{paste} = 3,4$ W/mK (PSX) | | | | | | 1,4 | | K/W |
| Dynamic | | | | | | | | | | |
| Peak recovery current | I_{RM} | $di/dt=6202$ A/μs $di/dt=5871$ A/μs $di/dt=5800$ A/μs | -5/15 | 350 | 50 | 25 | | 61,68 | | A |
| Reverse recovery time | t_{rr} | | | | | 125 | | 81,42 | ns | |
| | | | | | | 150 | | 86,91 | | |
| | | | | | | 25 | | 90,35 | | |
| Recovered charge | Q_r | | | | | 125 | | 3,1 | μC | |
| | | | | | | 150 | | 3,57 | | |
| | | 25 | | 0,435 | | | | | | |
| Reverse recovered energy | E_{rec} | 125 | | 0,897 | mWs | | | | | |
| | | 150 | | 1,03 | | | | | | |
| | | 25 | | 4295,76 | | | | | | |
| Peak rate of fall of recovery current | $(di_{rr}/dt)_{max}$ | 125 | | 3618,97 | A/μs | | | | | |
| | | 150 | | 3552,81 | | | | | | |
| | | 25 | | | | | | | | |



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Characteristic Values

| Parameter | Symbol | Conditions | | | | | Values | | | Unit |
|-----------|--------|--------------|--------------|--------------|--------------|------------------------|------------|-----|-----|------|
| | | V_{GS} [V] | V_{GE} [V] | V_{DS} [V] | V_{CE} [V] | I_D [A] I_F [A] | T_j [°C] | Min | Typ | |

Thermistor

Static

| | | | | | | | | | | |
|--------------------------------|----------------|-------------------------|--|--|--|-----|----|------|---|------|
| Rated resistance | R | | | | | 25 | | 22 | | kΩ |
| Deviation of R100 | $A_{R/R}$ | $R_{100} = 1484 \Omega$ | | | | 100 | -5 | | 5 | % |
| Power dissipation | P | | | | | 25 | | 130 | | mW |
| Power dissipation constant | d | | | | | 25 | | 1,5 | | mW/K |
| B-value | $B_{(25/50)}$ | Tol. $\pm 1 \%$ | | | | | | 3962 | | K |
| B-value | $B_{(25/100)}$ | Tol. $\pm 1 \%$ | | | | | | 4000 | | K |
| Vincotech Thermistor Reference | | | | | | | | | I | |

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.

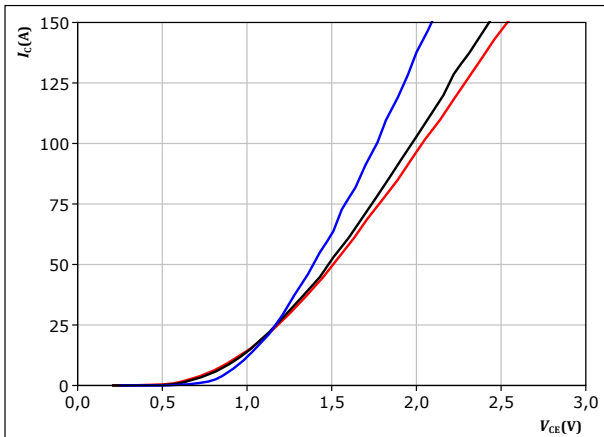


Inverter Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

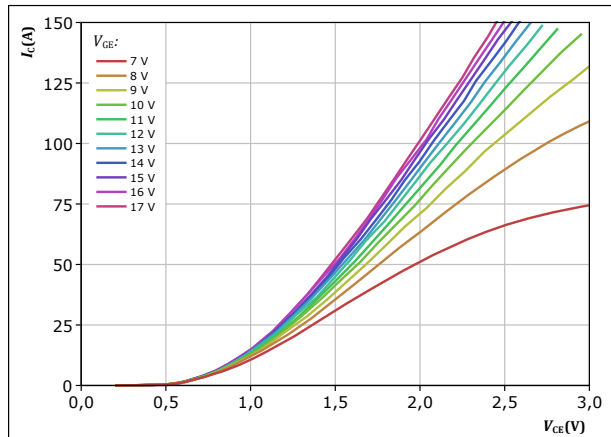


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j:$ 25 °C, 125 °C, 150 °C

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

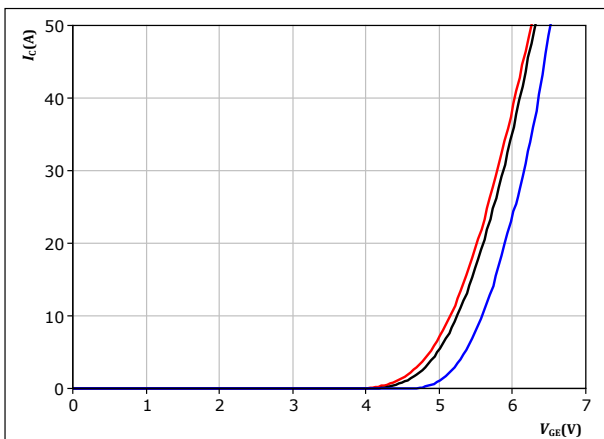


$t_p = 250 \mu s$
 $T_j = 150 \text{ °C}$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

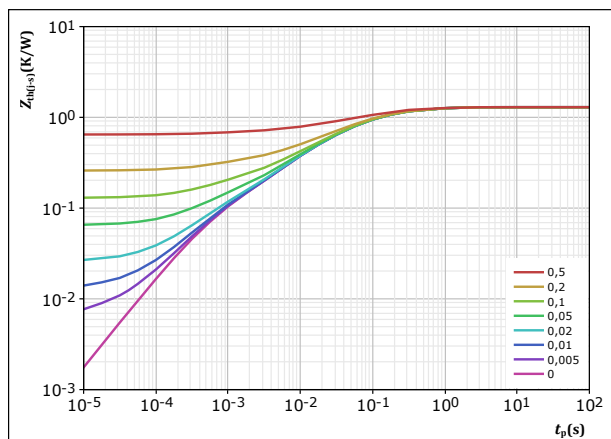


$t_p = 250 \mu s$
 $V_{CE} = 10 V$
 $T_j:$ 25 °C, 125 °C, 150 °C

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 1,294 \text{ K/W}$
IGBT thermal model values

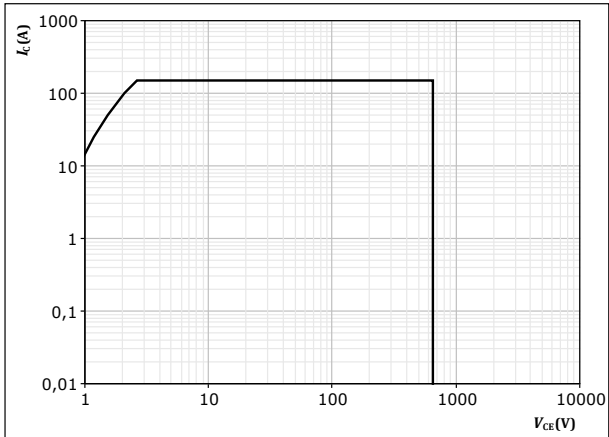
| R (K/W) | τ (s) |
|----------|------------|
| 2,09E-01 | 5,36E-01 |
| 6,00E-01 | 8,05E-02 |
| 3,10E-01 | 1,69E-02 |
| 1,08E-01 | 4,25E-03 |
| 6,63E-02 | 5,30E-04 |



Inverter Switch Characteristics

figure 5. IGBT

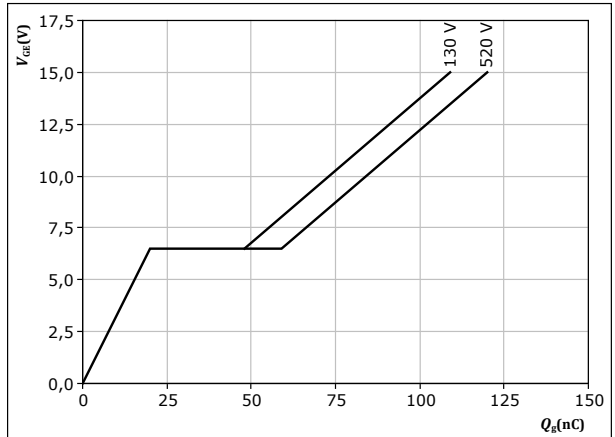
Safe operating area
 $I_C = f(V_{CE})$



D = single pulse
T_s = 80 °C
V_{GE} = 15 V
T_j = T_{jmax}

figure 6. IGBT

Gate voltage vs gate charge
 $V_{GE} = f(Q_g)$



I_C = 50 A
T_j = 25 °C



Inverter Diode Characteristics

figure 7. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

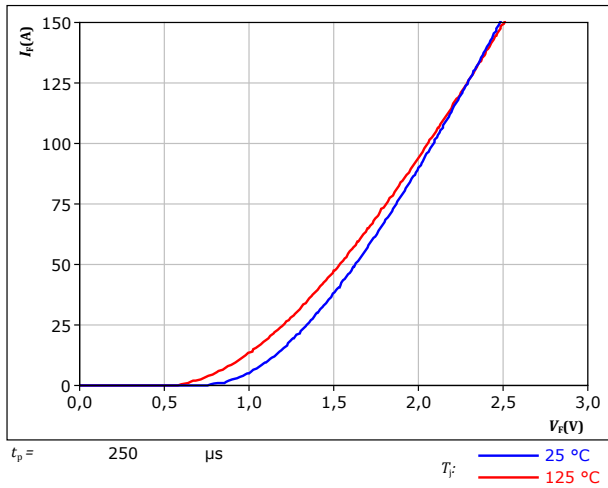
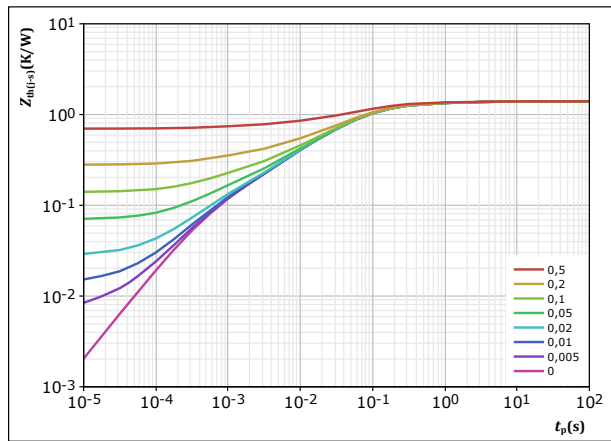


figure 8. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$

$R_{th(j-s)} = 1,399 \text{ K/W}$

FWD thermal model values

| $R \text{ (K/W)}$ | $\tau \text{ (s)}$ |
|-------------------|--------------------|
| 6,76E-02 | 3,05E+00 |
| 1,79E-01 | 3,50E-01 |
| 6,70E-01 | 7,08E-02 |
| 2,72E-01 | 1,81E-02 |
| 1,35E-01 | 4,13E-03 |
| 7,56E-02 | 5,11E-04 |

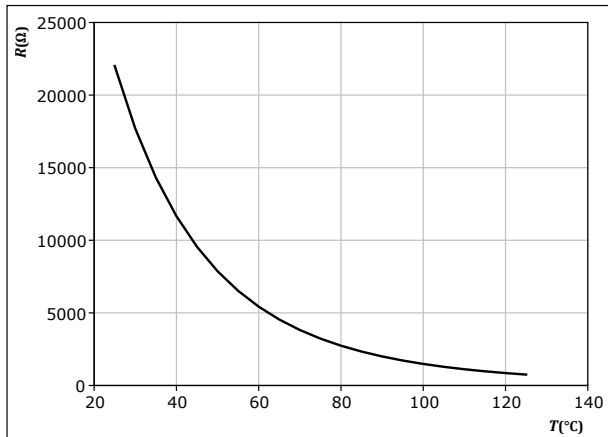


Thermistor Characteristics

figure 9. Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$

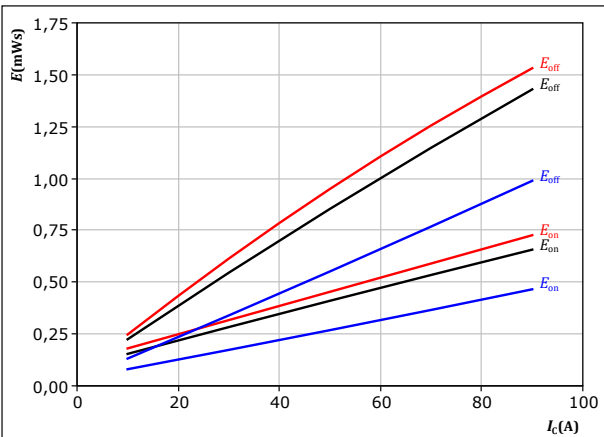




Inverter Switching Characteristics

figure 10. IGBT

Typical switching energy losses as a function of collector current
 $E = f(I_c)$

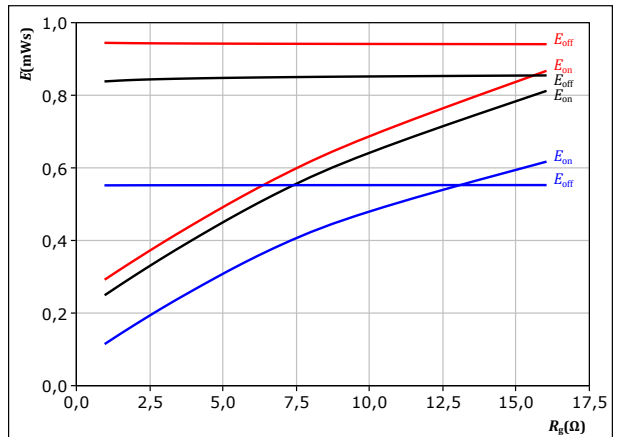


With an inductive load at

| | | | | |
|--------------|-------|----------|--------|----------|
| $V_{CE} =$ | 350 | V | $T_j:$ | — 25 °C |
| $V_{GE} =$ | -5/15 | V | | — 125 °C |
| $R_{gon} =$ | 4 | Ω | | — 150 °C |
| $R_{goff} =$ | 4 | Ω | | |

figure 11. IGBT

Typical switching energy losses as a function of IGBT turn on gate resistor
 $E = f(R_g)$

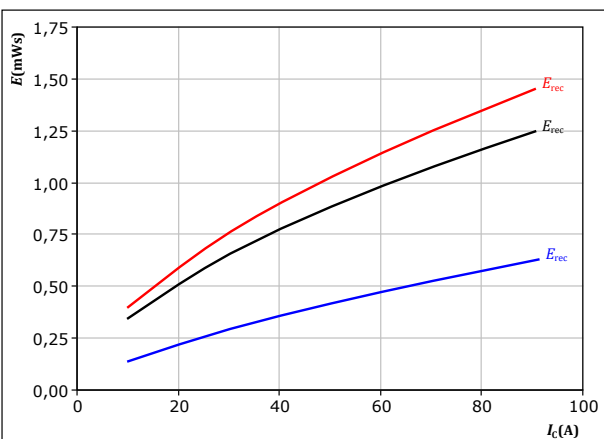


With an inductive load at

| | | | | |
|------------|-------|---|--------|----------|
| $V_{CE} =$ | 350 | V | $T_j:$ | — 25 °C |
| $V_{GE} =$ | -5/15 | V | | — 125 °C |
| $I_c =$ | 50 | A | | — 150 °C |

figure 12. FWD

Typical reverse recovered energy loss as a function of collector current
 $E_{rec} = f(I_c)$

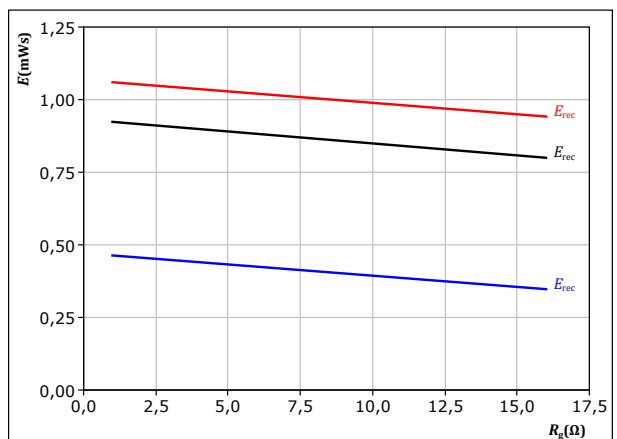


With an inductive load at

| | | | | |
|-------------|-------|----------|--------|----------|
| $V_{CE} =$ | 350 | V | $T_j:$ | — 25 °C |
| $V_{GE} =$ | -5/15 | V | | — 125 °C |
| $R_{gon} =$ | 4 | Ω | | — 150 °C |

figure 13. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor
 $E_{rec} = f(R_g)$



With an inductive load at

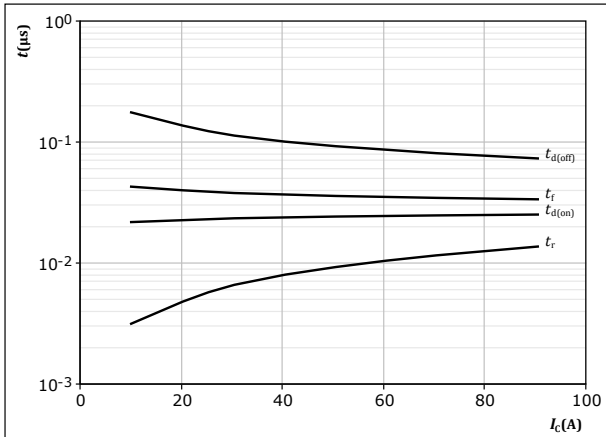
| | | | | |
|------------|-------|---|--------|----------|
| $V_{CE} =$ | 350 | V | $T_j:$ | — 25 °C |
| $V_{GE} =$ | -5/15 | V | | — 125 °C |
| $I_c =$ | 50 | A | | — 150 °C |



Inverter Switching Characteristics

figure 14. IGBT

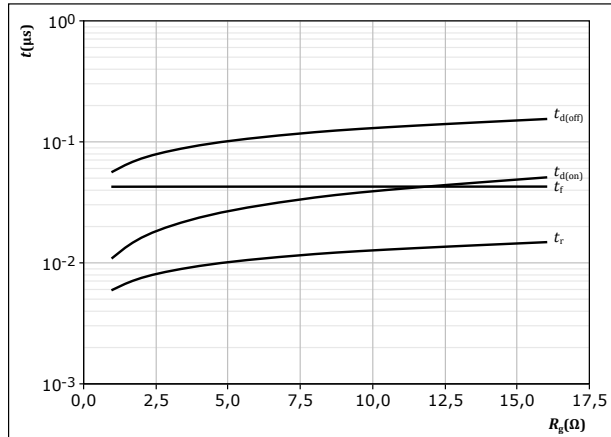
Typical switching times as a function of collector current
 $t = f(I_c)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = -5/15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$
 $R_{goff} = 4 \text{ } \Omega$

figure 15. IGBT

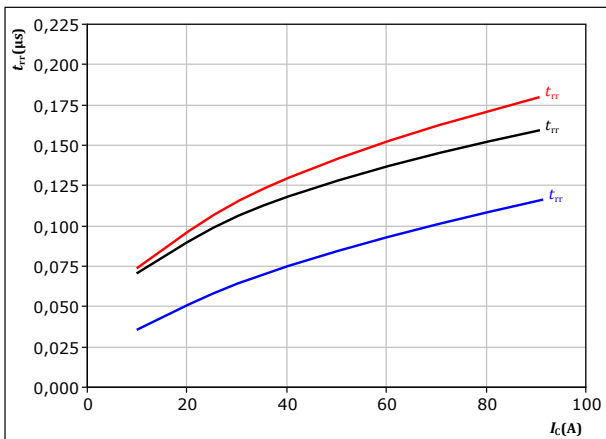
Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = -5/15 \text{ V}$
 $I_c = 50 \text{ A}$

figure 16. FWD

Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$

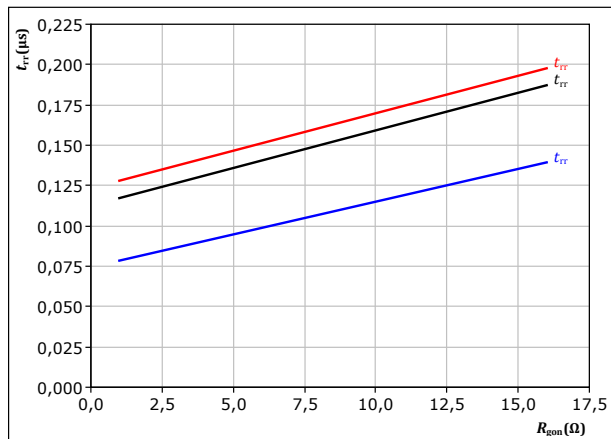


With an inductive load at
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = -5/15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 17. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = -5/15 \text{ V}$
 $I_c = 50 \text{ A}$

T_j :
— 25 °C
— 125 °C
— 150 °C

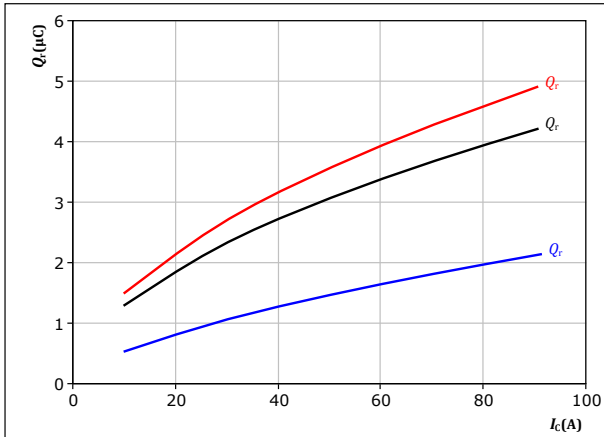


Inverter Switching Characteristics

figure 18. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

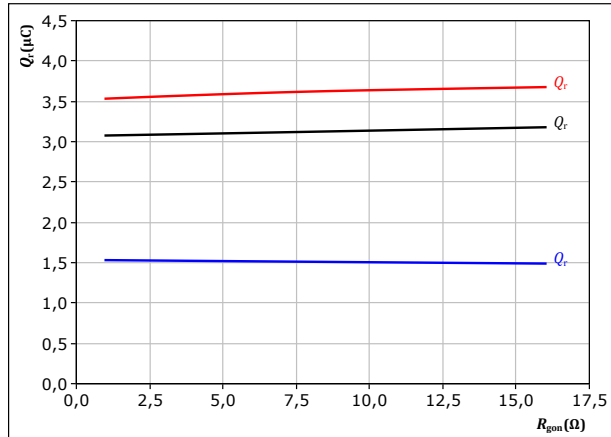
$V_{CE} = 350$ V
 $V_{GE} = -5/15$ V
 $R_{gon} = 4$ Ω

T_j : — 25 °C
— 125 °C
— 150 °C

figure 19. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

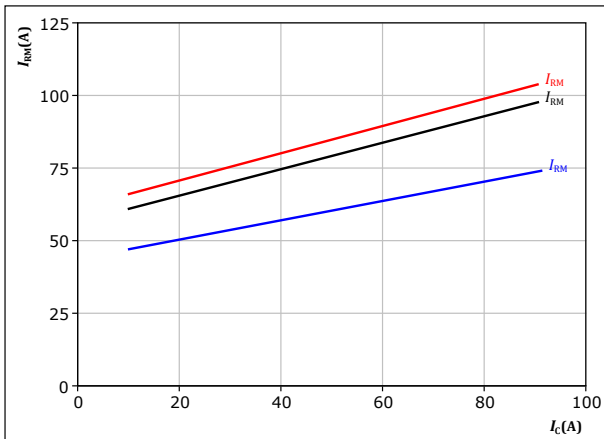
$V_{CE} = 350$ V
 $V_{GE} = -5/15$ V
 $I_c = 50$ A

T_j : — 25 °C
— 125 °C
— 150 °C

figure 20. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

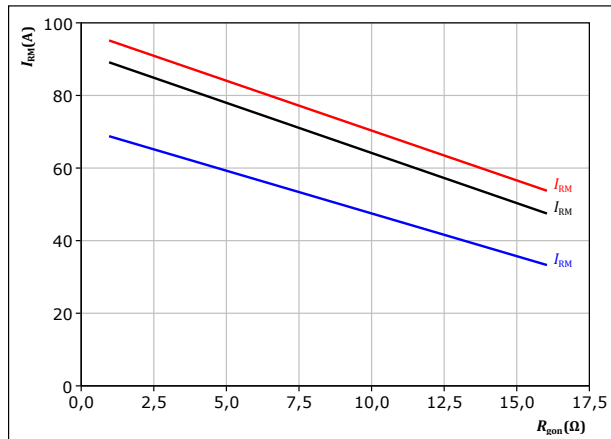
$V_{CE} = 350$ V
 $V_{GE} = -5/15$ V
 $R_{gon} = 4$ Ω

T_j : — 25 °C
— 125 °C
— 150 °C

figure 21. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = -5/15$ V
 $I_c = 50$ A

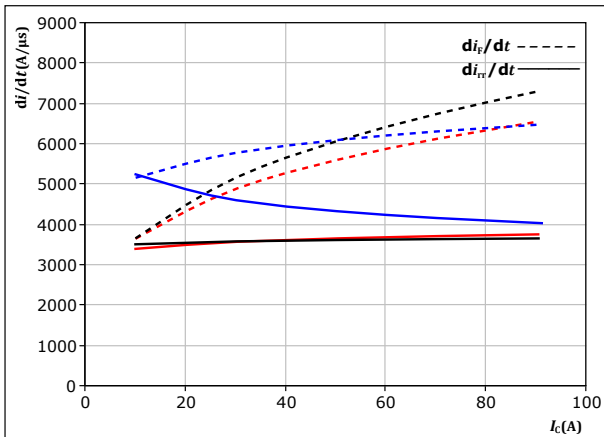
T_j : — 25 °C
— 125 °C
— 150 °C



Inverter Switching Characteristics

figure 22. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_{rr}/dt = f(I_C)$



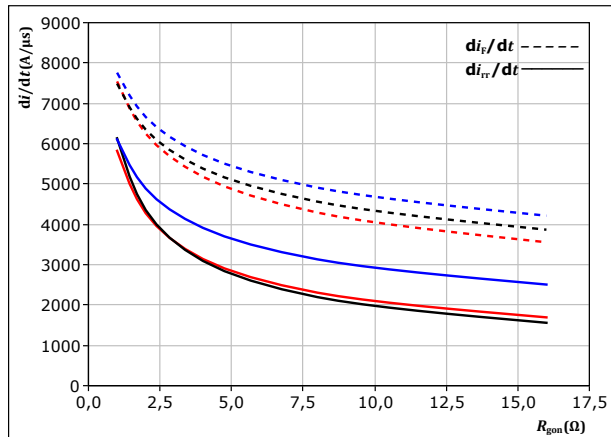
With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = -5/15$ V
 $R_{gon} = 4$ Ω

T_j : — 25 °C
 — 125 °C
 — 150 °C

figure 23. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_{rr}/dt = f(R_{gon})$



With an inductive load at

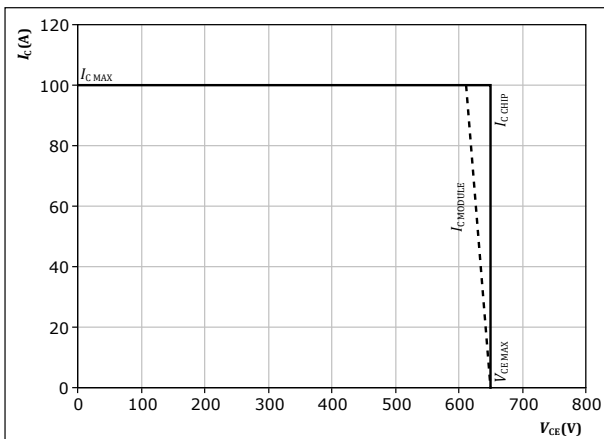
$V_{CE} = 350$ V
 $V_{GE} = -5/15$ V
 $I_C = 50$ A

T_j : — 25 °C
 — 125 °C
 — 150 °C

figure 24. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At $T_j = 150$ °C
 $R_{gon} = 4$ Ω
 $R_{goff} = 4$ Ω



Inverter Switching Definitions

figure 25. IGBT
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

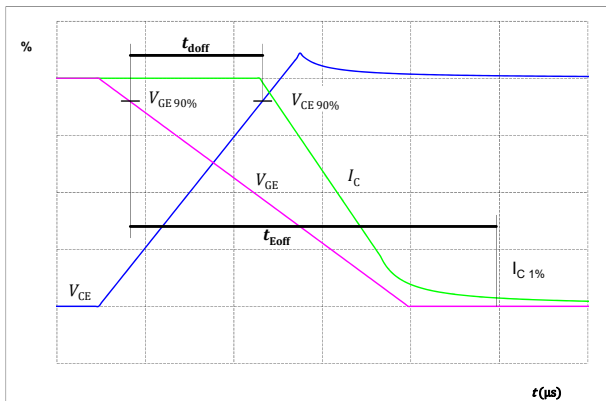


figure 26. IGBT
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

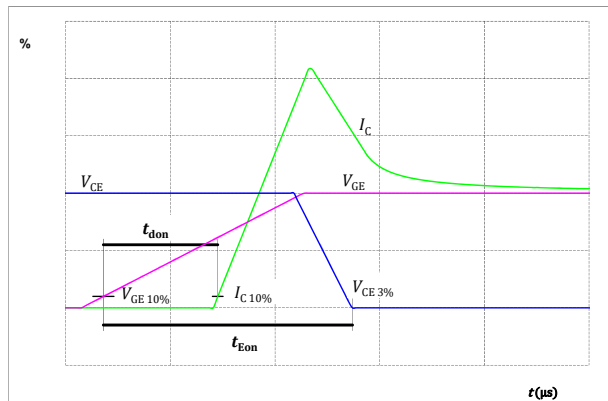


figure 27. IGBT
Turn-off Switching Waveforms & definition of t_f

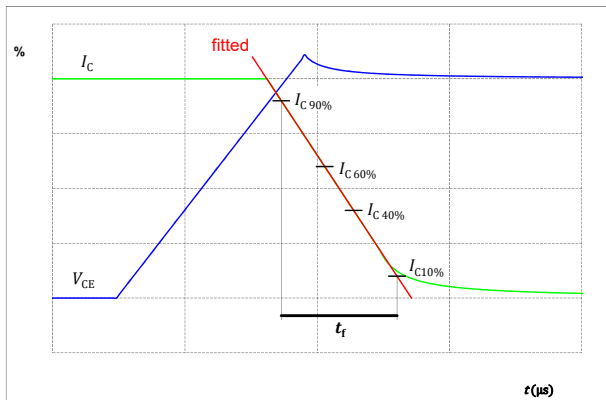
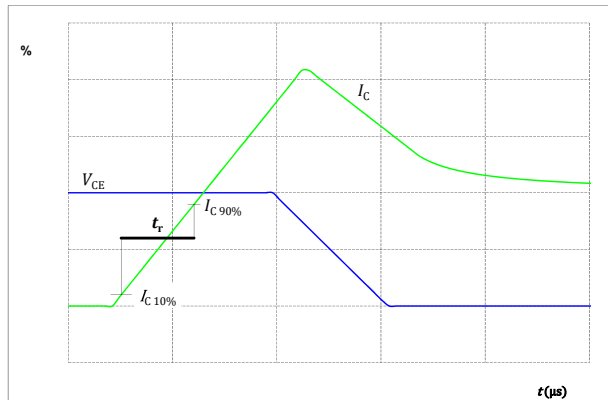


figure 28. IGBT
Turn-on Switching Waveforms & definition of t_r





Inverter Switching Definitions

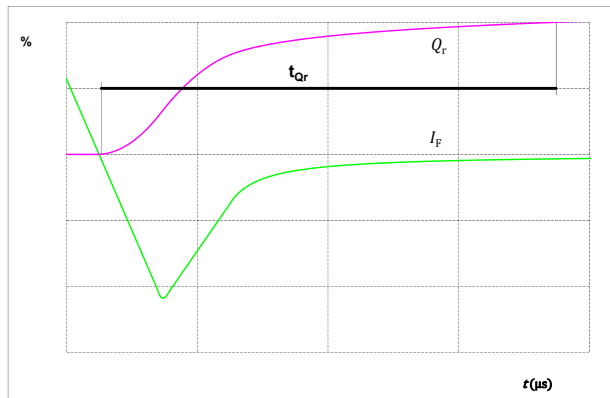
figure 29. FWD

Turn-off Switching Waveforms & definition of t_{rr}



figure 30. FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)





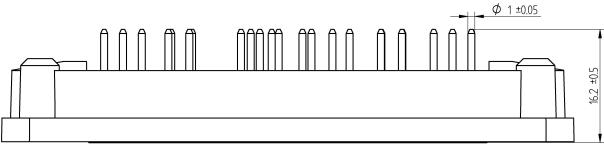
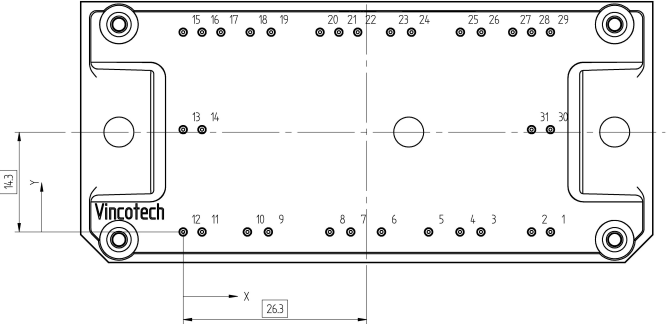
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10-FY076PA050S501-L822F58
datasheet

| Ordering Code | |
|--|-------------------------------|
| Version | Ordering Code |
| Without thermal paste | 10-FY076PA050S501-L822F58 |
| With thermal paste (5,2 W/mK, PTM6000HV) | 10-FY076PA050S501-L822F58-/7/ |
| With thermal paste (3,4 W/mK, PSX-P7) | 10-FY076PA050S501-L822F58-/3/ |

| Marking | | | | | | |
|---------|-------------------|---|----------------------------|-------------------------------|--------------------------|-----------------------|
| | Text | Name NN-NNNNNNNNNNNNNN- TTTTTIVV | Date code WWYY | UL & VIN UL VIN | Lot LLLLL | Serial SSSS |
| | Datamatrix | Type&Ver TTTTTIVV | Lot number LLLLL | Serial SSSS | Date code WWYY | |

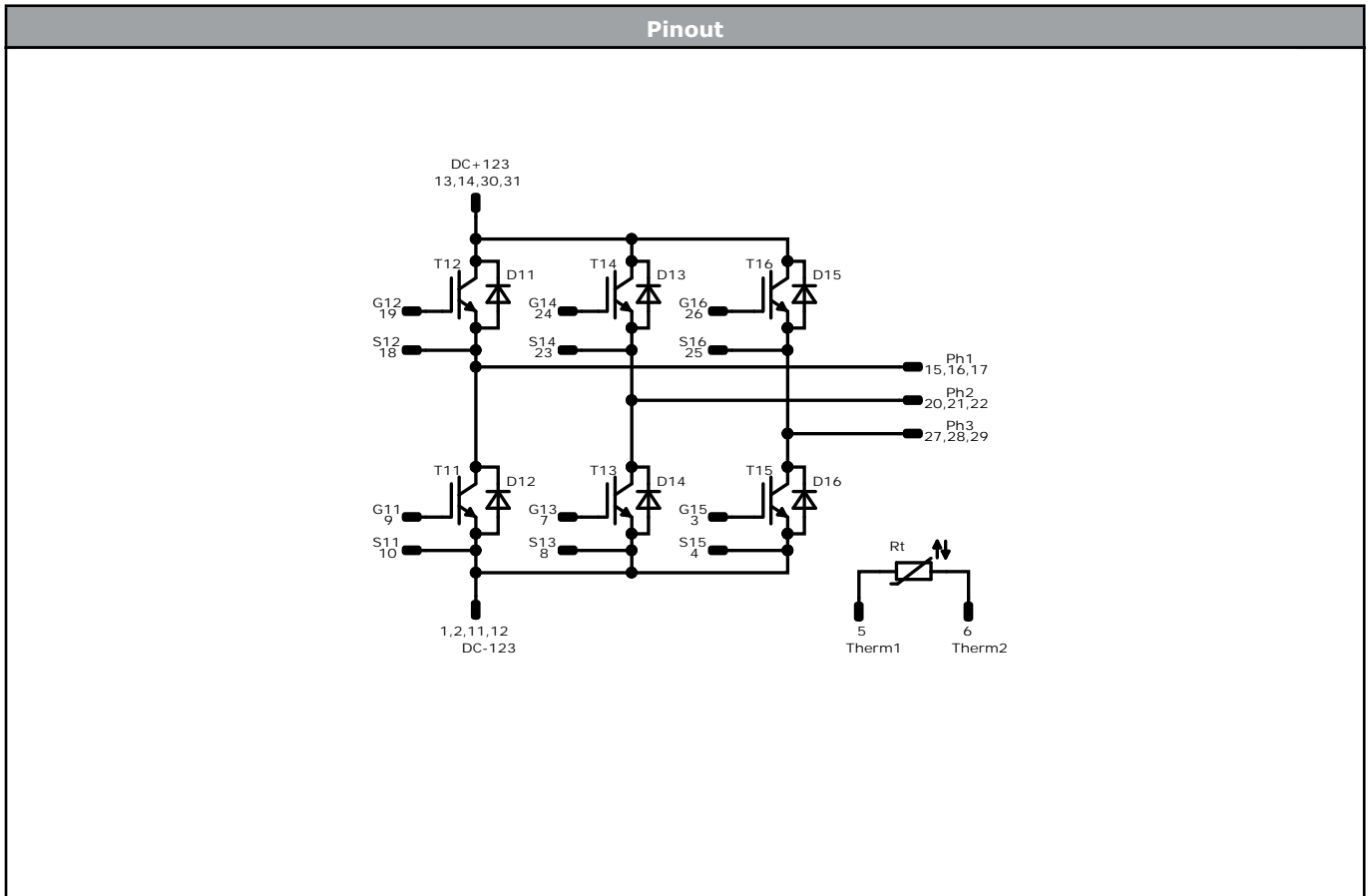
| Pin table [mm] | | | |
|----------------|-------|-------|----------|
| Pin | X | Y | Function |
| 1 | 52,6 | 0 | DC- |
| 2 | 49,9 | 0 | DC- |
| 3 | 42,65 | 0 | G6 |
| 4 | 39,65 | 0 | S6 |
| 5 | 35,15 | 0 | NTC1 |
| 6 | 28,4 | 0 | NTC2 |
| 7 | 24 | 0 | G4 |
| 8 | 21 | 0 | S4 |
| 9 | 12,2 | 0 | G2 |
| 10 | 9,2 | 0 | S2 |
| 11 | 2,7 | 0 | DC- |
| 12 | 0 | 0 | DC- |
| 13 | 0 | 14,65 | DC+ |
| 14 | 2,7 | 14,65 | DC+ |
| 15 | 0 | 28,6 | U |
| 16 | 2,7 | 28,6 | U |
| 17 | 5,4 | 28,6 | U |
| 18 | 9,6 | 28,6 | S1 |
| 19 | 12,6 | 28,6 | G1 |
| 20 | 19,6 | 28,6 | V |
| 21 | 22,3 | 28,6 | V |
| 22 | 25 | 28,6 | V |
| 23 | 29,7 | 28,6 | S3 |
| 24 | 32,7 | 28,6 | G3 |
| 25 | 39,7 | 28,6 | S5 |
| 26 | 42,7 | 28,6 | G5 |
| 27 | 47,2 | 28,6 | W |
| 28 | 49,9 | 28,6 | W |
| 29 | 52,6 | 28,6 | W |
| 30 | 52,6 | 14,65 | DC+ |
| 31 | 49,9 | 14,65 | DC+ |

Tolerance of pinpositions: ±0,5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance



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| Identification | | | | | |
|------------------------------|------------------|----------------|----------------|-----------------|----------------|
| ID | Component | Voltage | Current | Function | Comment |
| T11, T12, T13, T14, T15, T16 | IGBT | 650 V | 50 A | Inverter Switch | |
| D11, D12, D13, D14, D15, D16 | FWD | 650 V | 50 A | Inverter Diode | |
| Rt | Thermistor | | | Thermistor | |




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| Packaging instruction | | | | |
|---------------------------------------|------|----------|------|--------|
| Standard packaging quantity (SPQ) 100 | >SPQ | Standard | <SPQ | Sample |

| Handling instruction |
|---|
| Handling instructions for <i>flow 1</i> packages see vincotech.com website. |

| Package data |
|--|
| Package data for <i>flow 1</i> packages see vincotech.com website. |

| Vincotech thermistor reference |
|--|
| See Vincotech thermistor reference table at vincotech.com website. |

| UL recognition and file number |
|---|
| This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.  |

| Document No.: | Date: | Modification: | Pages |
|---------------------------------|--------------|---------------|-------|
| 10-FY076PA050S501-L822F58-D1-14 | 21 Nov. 2023 | | |

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.